

ABSTRACT OF THE DISCLOSURE

A recess for fully receiving an electronic component and a window opened from the bottom of the recess to the bottom surface of a metal substrate are formed in the metal substrate. A wiring board is bonded to the underside of the metal substrate, and the electronic component is fixed to the bottom of the recess. Input and output terminals of the electronic component are connected to electrode pads of the wiring board exposed within the window using wire bonding. A metal lid is bonded to the top surface of the metal substrate to close the opening of the recess. Electromagnetic waves generated by the electronic component are confined to the electronic device because the electronic device is surrounded by the metal substrate, the metal lid, and a ground electrode disposed on the wiring board. Heat dissipation performance is assured because the electronic component is connected to the metal substrate.